

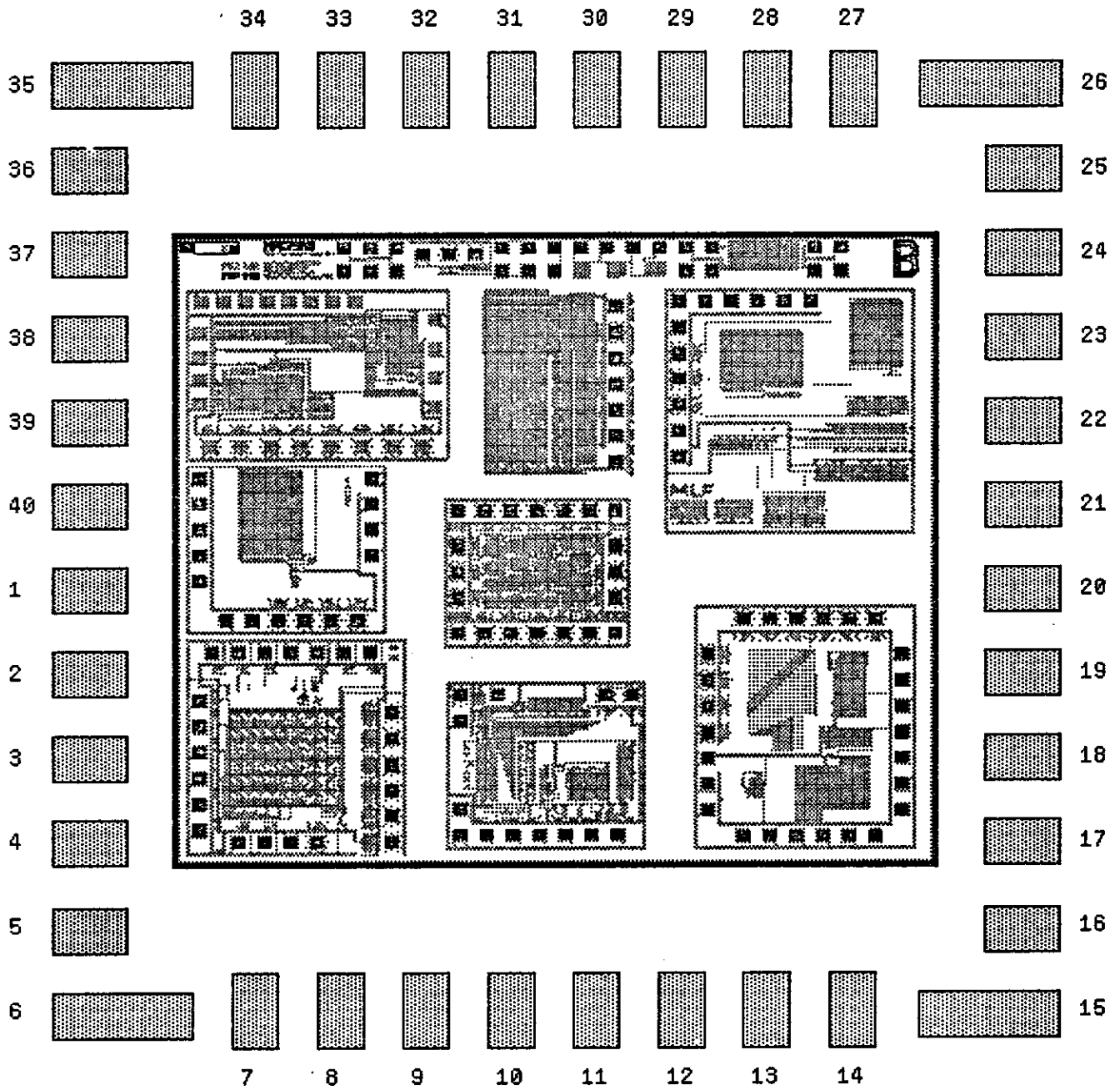
6. Bonding Maps for the 12 Project Die Types

A marked-up wire-bonding map is included with every packaged chip being shipped to the project lab coordinators. These individually "customized", marked-up maps document the package pin-outs of the projects, so that project designers can determine how hook up the packages for functional testing of their projects.

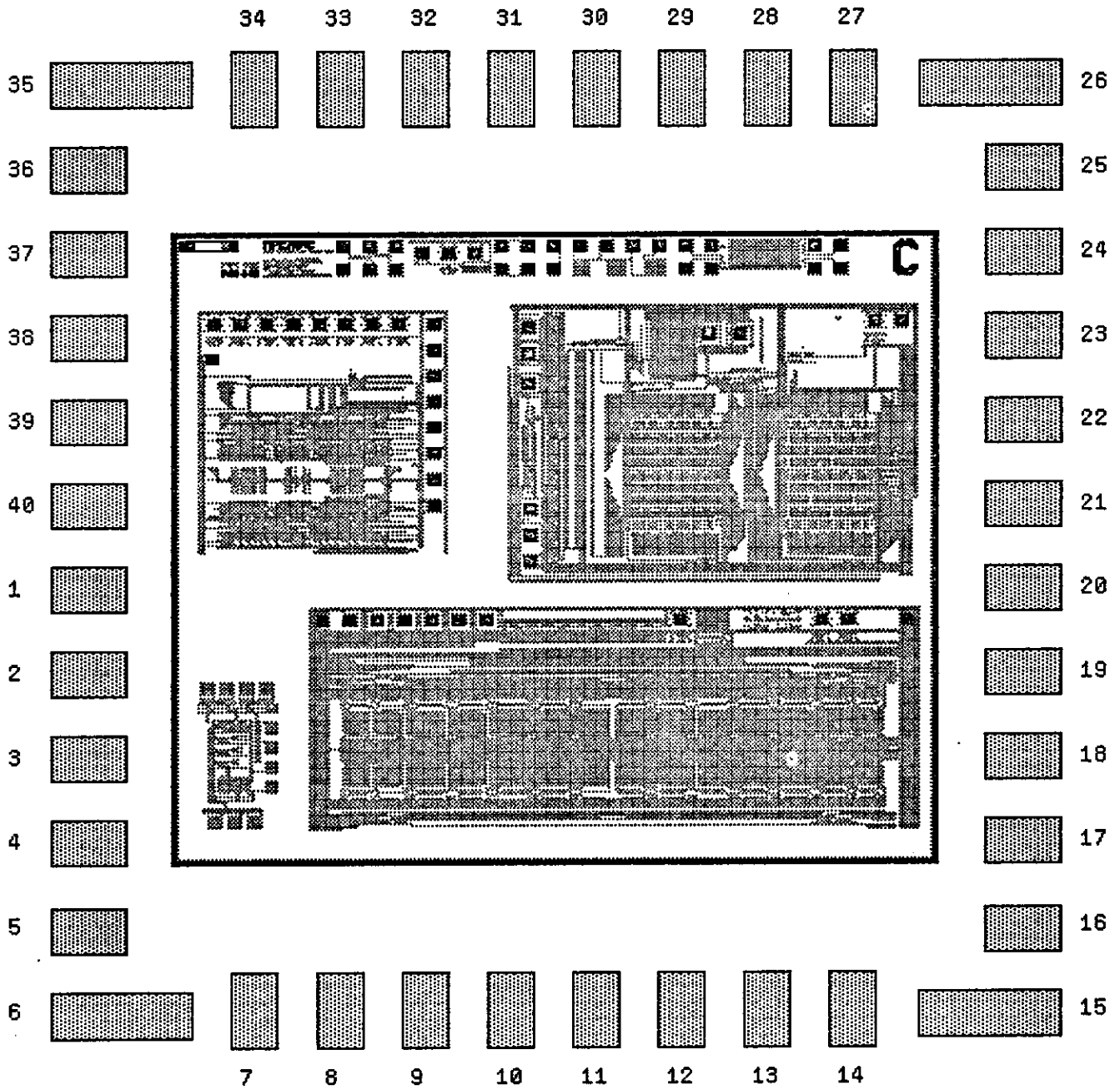
In addition to the packaged chips, each of the project lab coordinators is also being sent a selection of diced but unmounted chips. The following section contains a full set of *unmarked* wire-bonding maps for the 12 different project die-types. Copies of these maps may be marked-up to document the pin-outs of any of the unmounted chips that are packaged later on (these will prove especially useful if later packaging leads to different pin-outs than for the original group of chips).

These maps also convey some notion of the scope and complexity of the various MPC79 designs, and of the overall MPC79 effort.

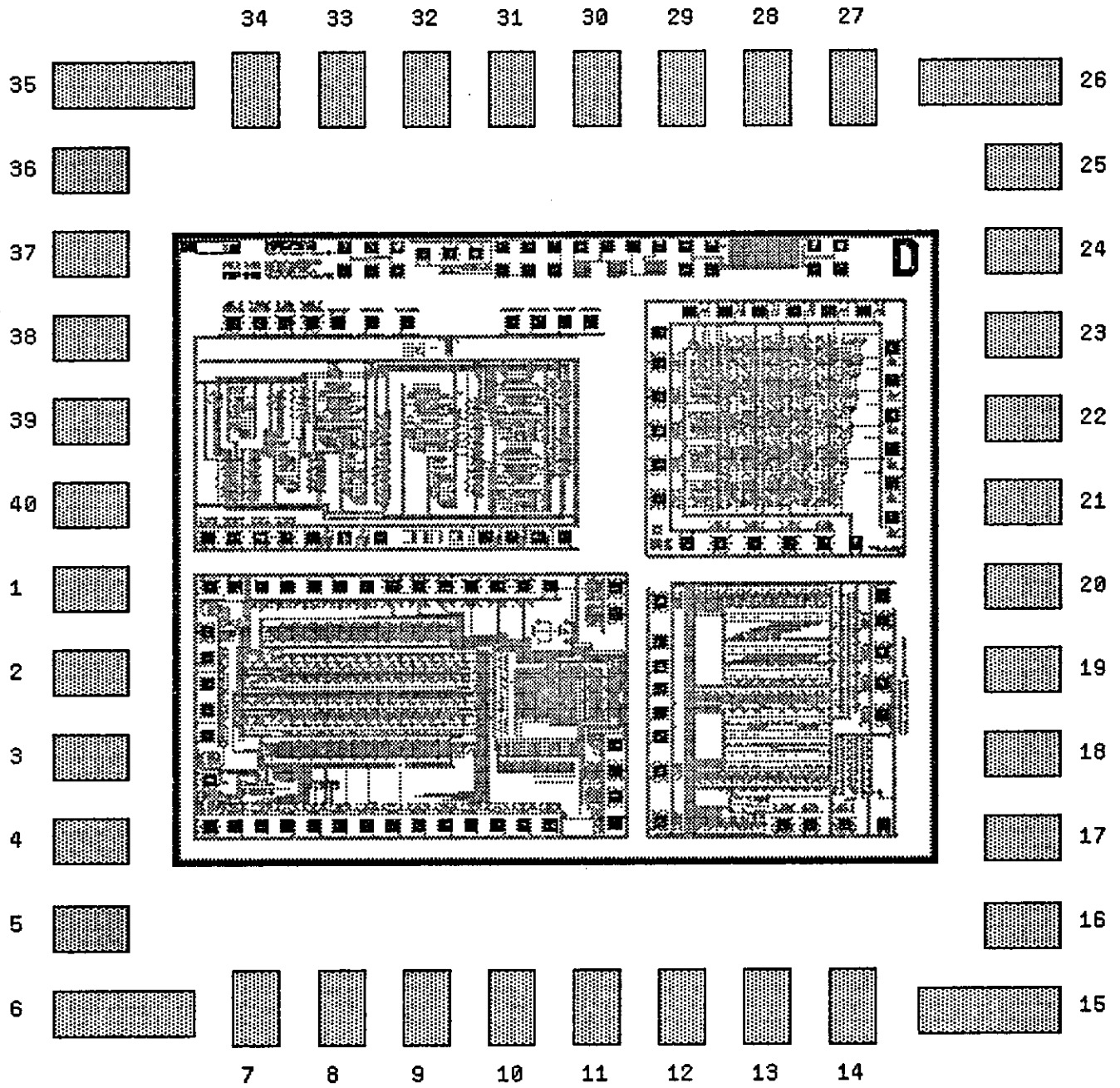
MPC79 AB



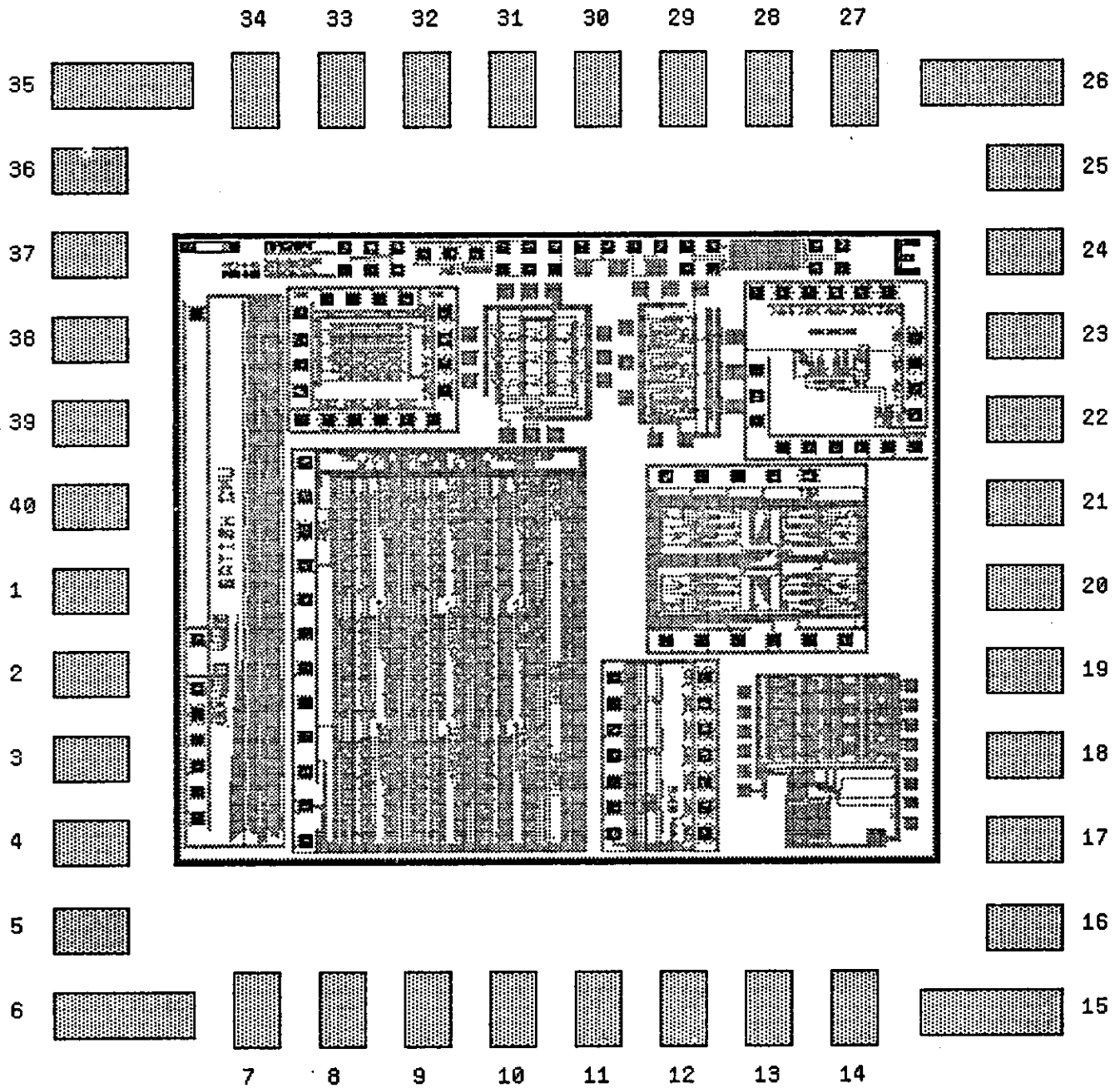
MPC79 AC



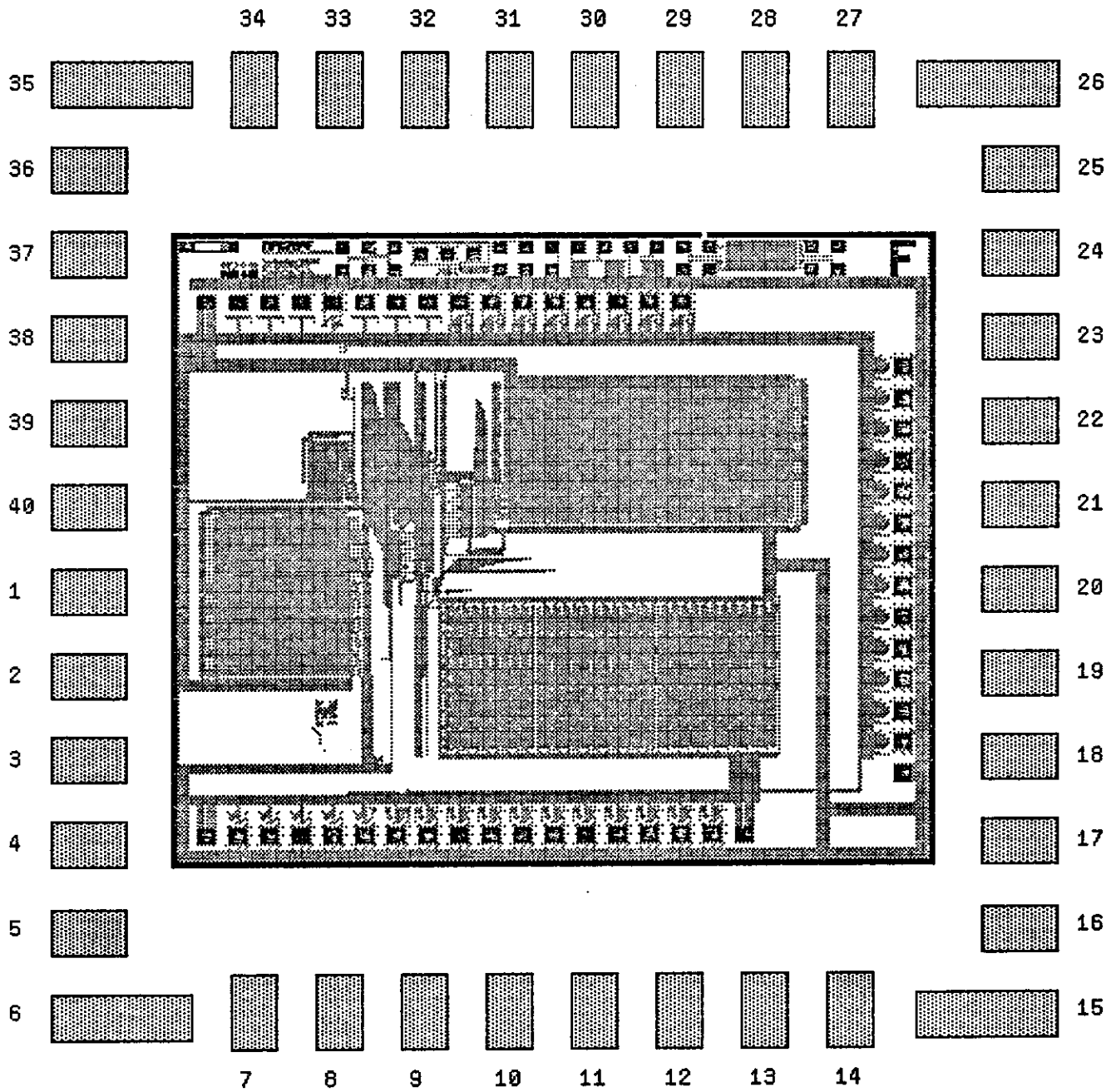
MPC79 AD



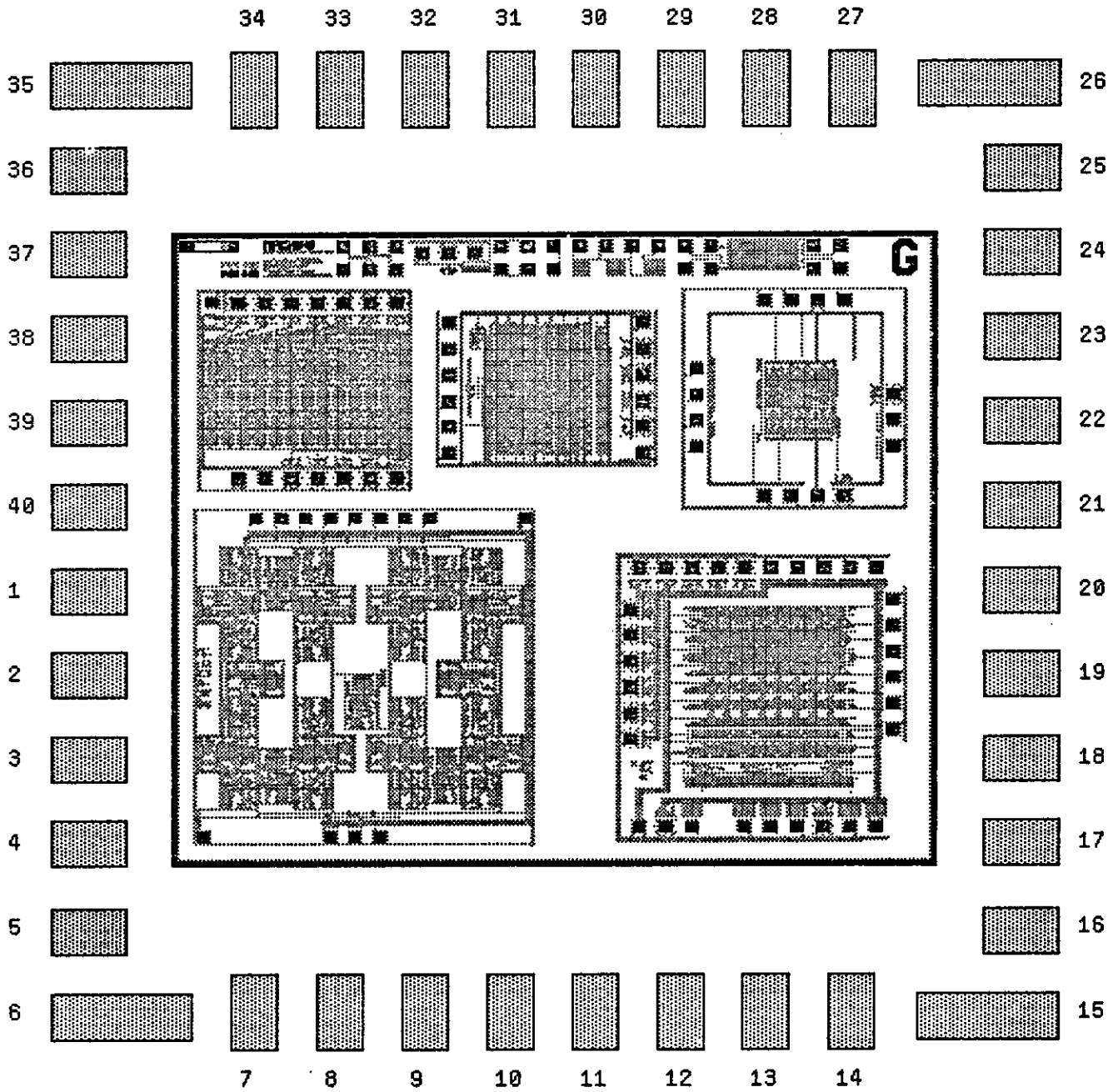
MPC79 AE



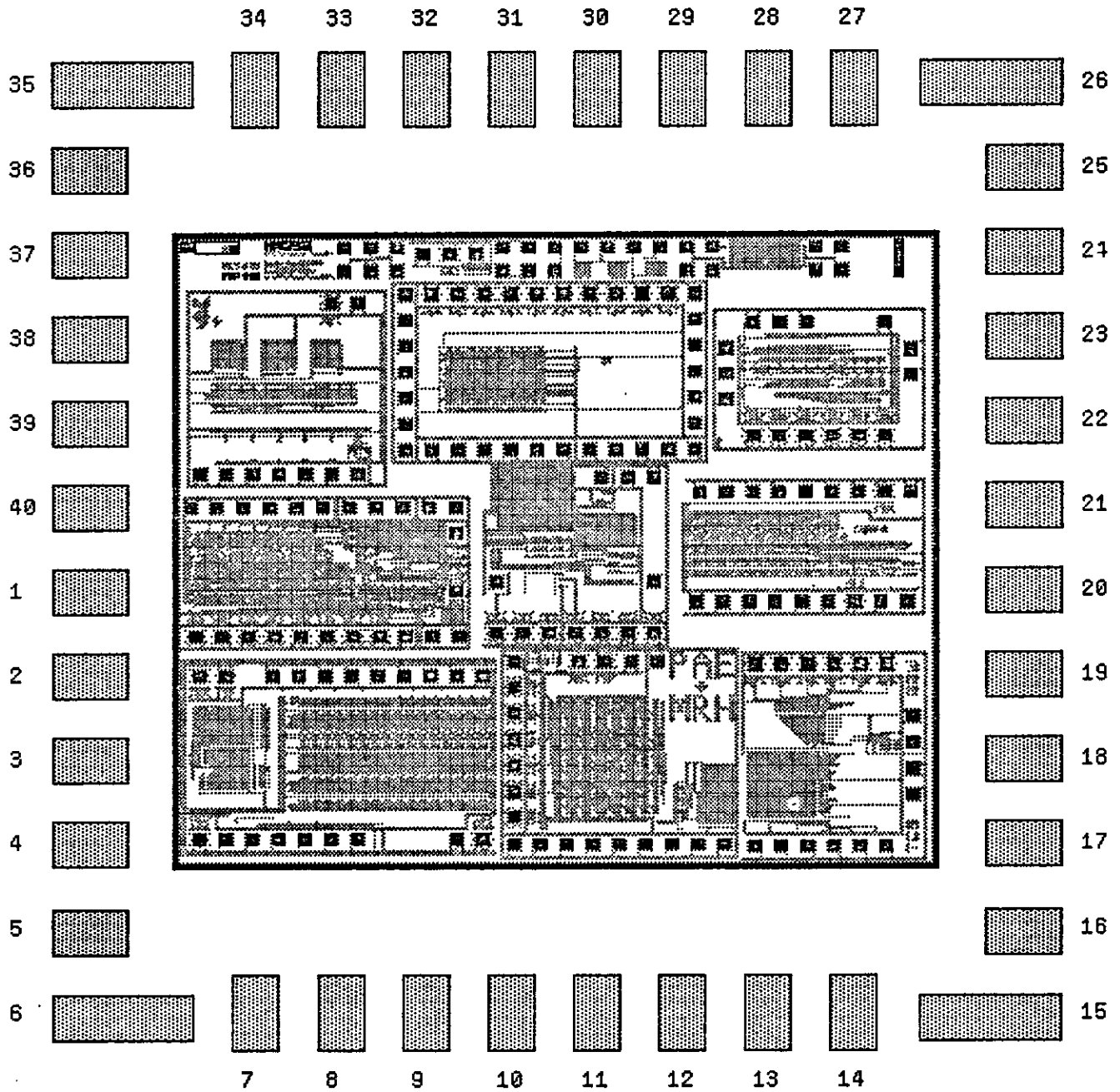
MPC79 AF



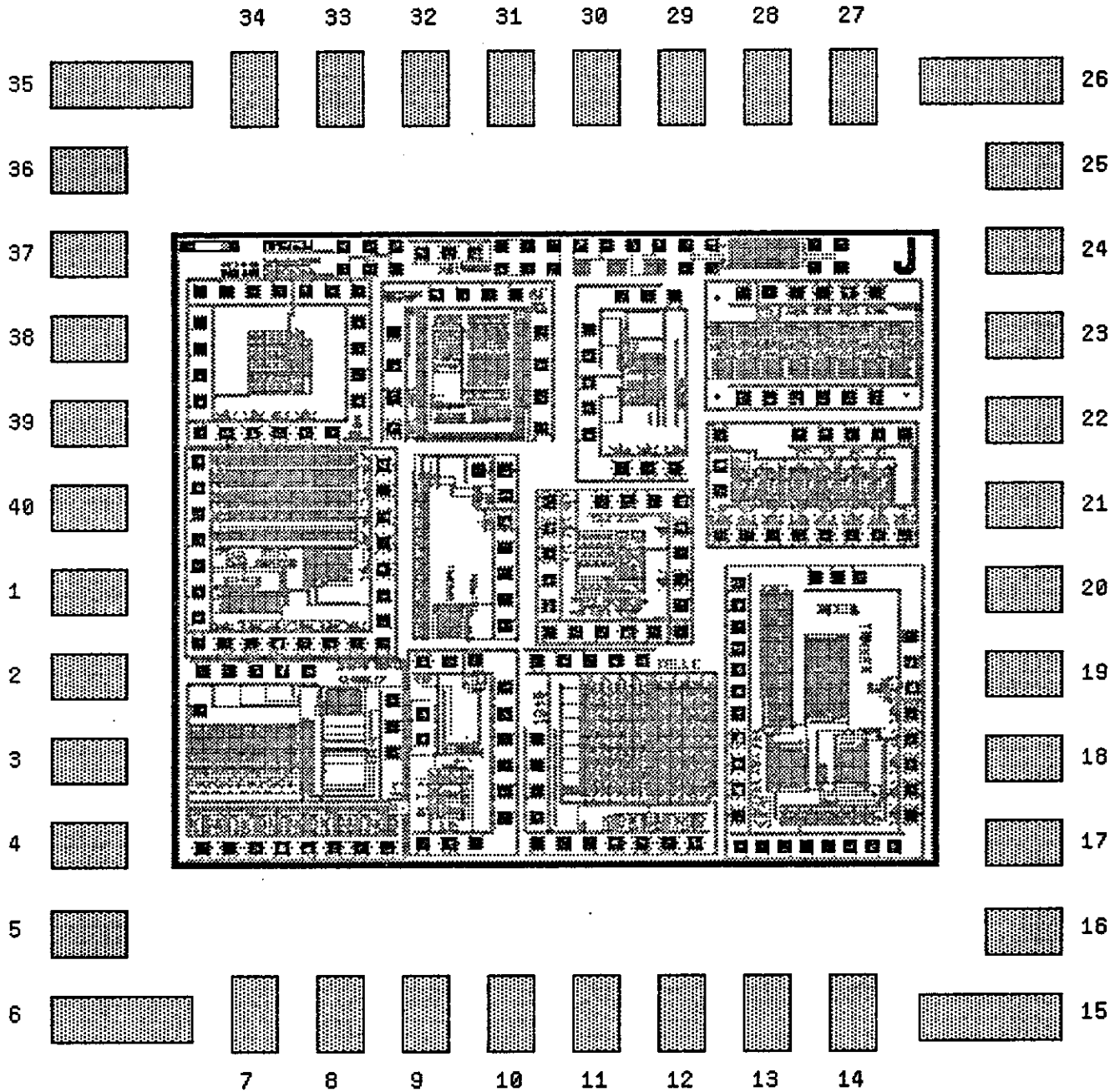
MPC79 A6



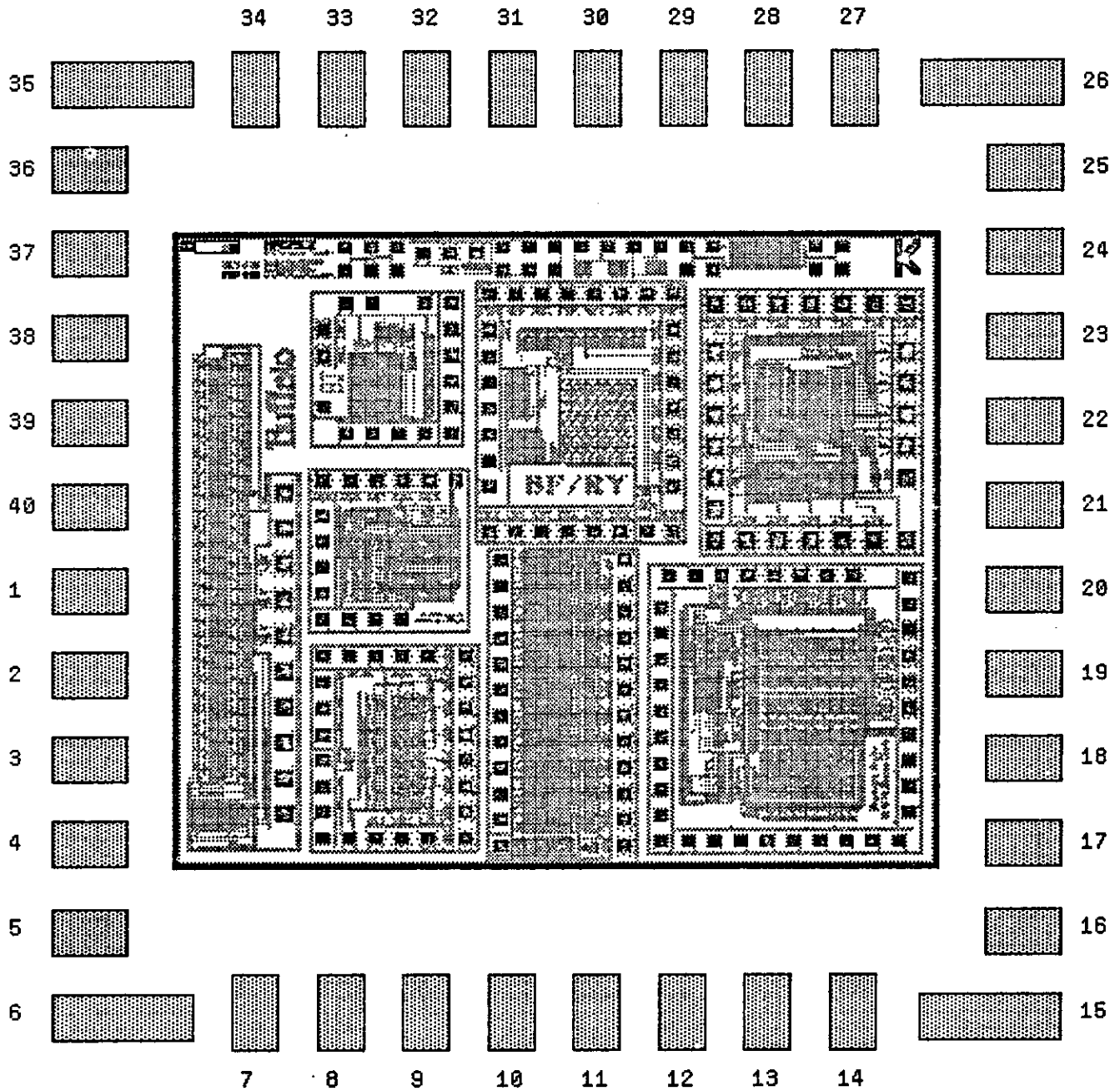
MPC79 BI



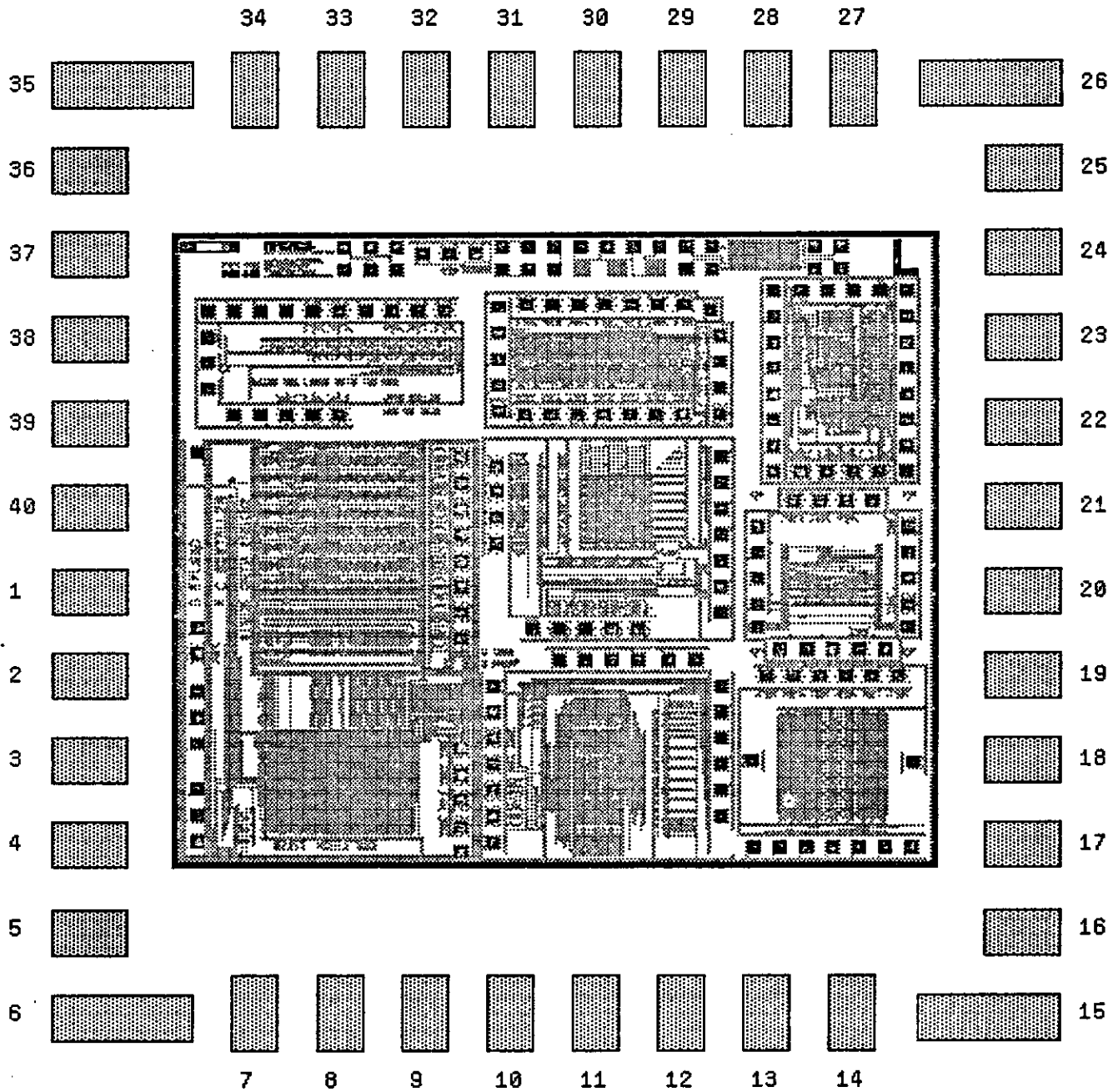
MPC79 BJ



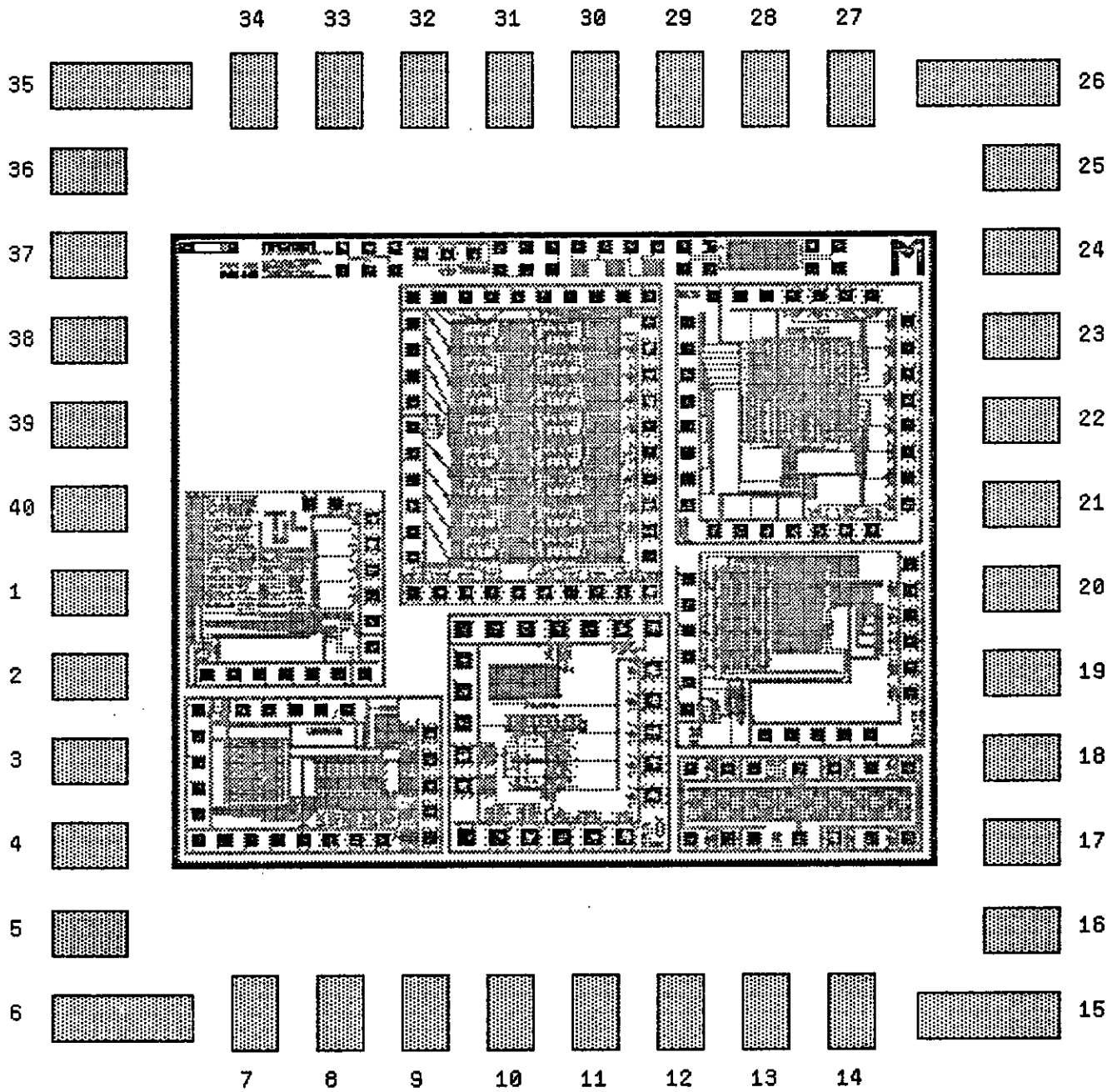
MPC79 BK



MPC79 8L



MPC79 8M



MPC79 BN

